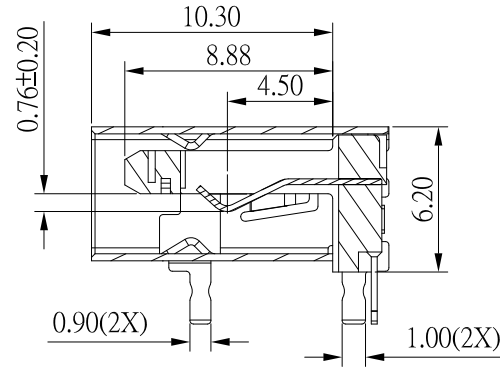
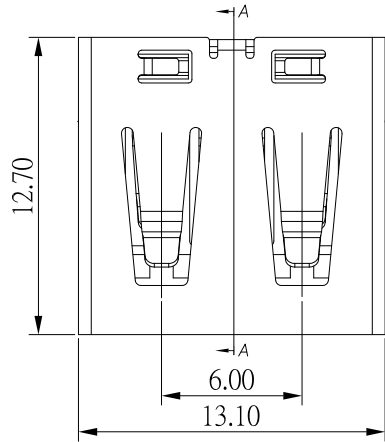


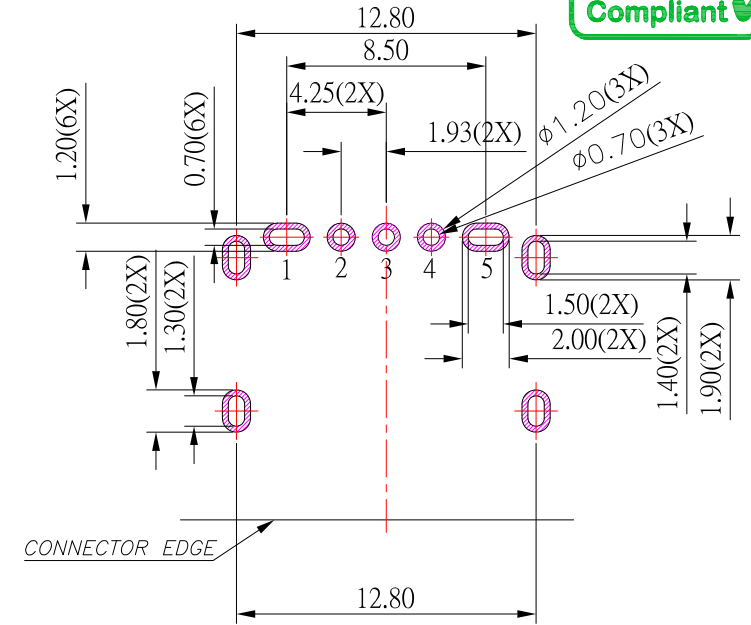


# SUA-110H46-xx-S277

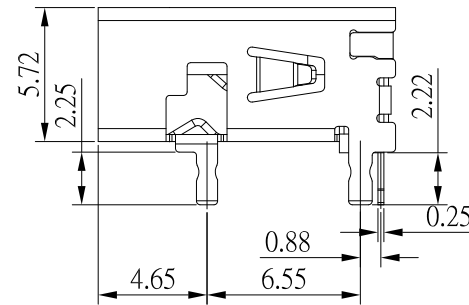
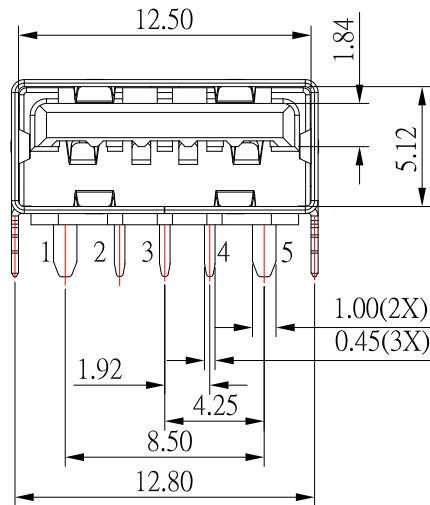
鍍層厚度 :	Color :
Blank : 1u"	Black : B
2 : 15u"	Green : GR
3 : 30u"	



SECTION:A-A



RECOMMENDED PCB LAYOUT



NOTE:

1.MATERIAL:

- 1.1 Housing: PA10T
- 1.2 Contact: Copper Alloy
- 1.3 Shell: SUS

2.Finish:

- 2.1 Contact: Plated Gold in Mating Area ;  
Tin Plated on Solder Balls ;  
Nickel under plated overall
- 2.2 Shell: Nickel under Plated surface layer

3.SPECIFICATION:

- 3.1 Current Rate: 5.0 A(VBUS & GND)
- 3.2 insulator Resistance:100MΩ Min
- 3.3 Dielectric Strength: 100V AC
- 3.4 Contact Resistance: 30mΩ Max
- 3.5 Operation Temperature: -25°C ~ +85°C
- 3.6 Insertion Force: 3.57 kgf Max
- 3.7 Extraction Force: 1.02 kgf Min

4	更新圖面	Jack	052620
3	更新為A0版	Jack	101817
2	新增顏色編碼	Jack	100317
1	新增pin編號及圖示	Jack	092217
ITEM NO.	DESCRIPTION	DRAWN	DATE



TOLERANCE UNLESS OTHERWISE STATED :

Up to 5	±0.2
Above 5 ~ 15	±0.3
Above 15 ~ 30	±0.4
Above 30 ~ 50	±0.5
Angle	±0.3°

3RD. ANGEL'S

DRAWN BY:	DATE	MAT'L	TITLE	CONNECTOR
Jack Lu	05/26/20			
CHECKED BY:	DATE	FINISH	MODLE	USB AF 2.0 90度 DIP 5PIN 直腳 無捲邊
Jacky Chen	05/26/20			
APPROVED BY:	DATE	SCALE	DWG NO.	SUA-110H46-xx-S277
Tony Kao	05/26/20	1 : 1		
		SHEET NO.	PART NO.	SUA-110H46-xx-S277
		1 of 1		
			SIZE	A4
			VER	R4